

## 40 A, 1200 V short circuit rugged IGBT with Ultrafast diode

### Features

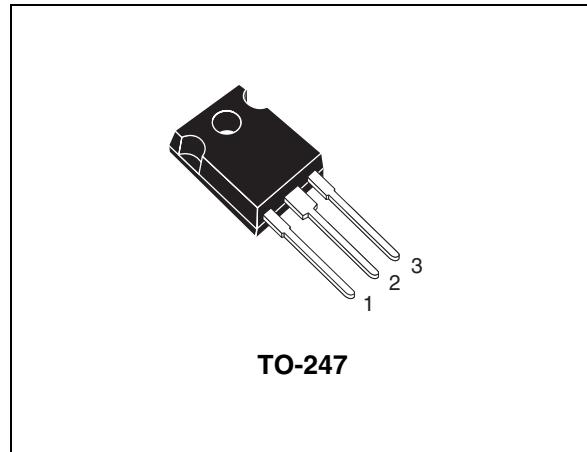
- Low on-losses
- High current capability
- Low gate charge
- Short circuit withstand time 10  $\mu$ s
- IGBT co-packaged with Ultrafast free-wheeling diode

### Applications

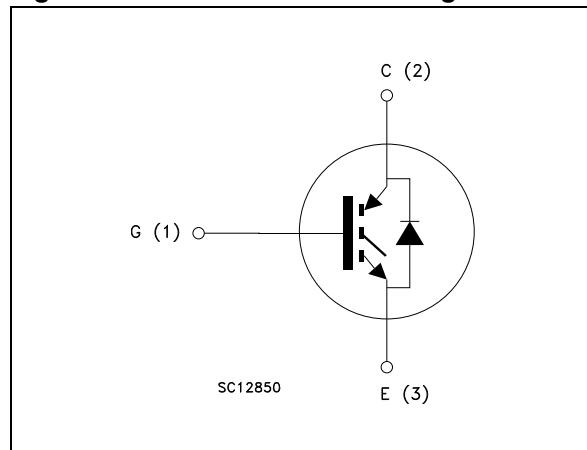
- Motor control

### Description

This Ultrafast IGBT is developed using a new planar technology to yield a device with tighter switching energy variation ( $E_{off}$ ) versus temperature. The suffix "W" denotes a subset of products designed for high switching frequency operation (over 100 kHz)".



**Figure 1. Internal schematic diagram**



**Table 1. Device summary**

Order codes	Markings	Package	Packaging
STGW40N120KD	GW40N120KD	TO-247	Tube
STGWA40N120KD	GWA40N120KD	TO-247 long leads	Tube

## Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-emitter voltage ( $V_{GE} = 0$ )	1200	V
$I_C^{(1)}$	Continuous collector current at $T_C = 25^\circ\text{C}$	80	A
$I_C^{(1)}$	Continuous collector current at $T_C = 100^\circ\text{C}$	40	A
$I_{CL}^{(2)}$	Turn-off latching current	85	A
$I_{CP}^{(3)}$	Pulsed collector current	120	A
$V_{GE}$	Gate-emitter voltage	$\pm 25$	V
$t_{SCW}$	Short circuit withstand time, $V_{CE} = 0.5 V_{(BR)CES}$ $T_j = 125^\circ\text{C}$ , $R_G = 10 \Omega$ , $V_{GE} = 12 \text{ V}$	10	$\mu\text{s}$
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$	240	W
$I_F$	Diode RMS forward current at $T_C = 25^\circ\text{C}$	30	A
$I_{FSM}$	Surge non repetitive forward current $t_p = 10 \text{ ms}$ sinusoidal	100	A
$T_j$	Operating junction temperature	- 55 to 125	$^\circ\text{C}$

1. Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{j(\max)} - T_C}{R_{thj-c} \times V_{CE(sat)(\max)}(T_{j(\max)}, I_C(T_C))}$$

2.  $V_{clamp} = 80\%$  of  $V_{CES}$ ,  $T_j = 125^\circ\text{C}$ ,  $R_G = 10 \Omega$ ,  $V_{GE} = 15 \text{ V}$
3. Pulse width limited by maximum junction temperature and turn-off within RBSOA

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case IGBT	0.42	$^\circ\text{C/W}$
$R_{thj-case}$	Thermal resistance junction-case diode	1.6	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	50	$^\circ\text{C/W}$

## 2 Electrical characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified.

**Table 4. Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CES}}$	Collector-emitter breakdown voltage ( $V_{GE} = 0$ )	$I_C = 1 \text{ mA}$	1200			V
$V_{CE(\text{sat})}$	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}, I_C = 30 \text{ A}$ $V_{GE} = 15 \text{ V}, I_C = 30 \text{ A}, T_J = 125^\circ\text{C}$		2.8 2.7	3.85	V
$V_{GE(\text{th})}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 1 \text{ mA}$	4.5		6.5	V
$I_{CES}$	Collector cut-off current ( $V_{GE} = 0$ )	$V_{CE} = 1200 \text{ V}$ $V_{CE} = 1200 \text{ V}, T_J = 125^\circ\text{C}$			500 10	$\mu\text{A}$ mA
$I_{GES}$	Gate-emitter leakage current ( $V_{CE} = 0$ )	$V_{GE} = \pm 20 \text{ V}$			$\pm 100$	nA

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input capacitance			2577		pF
$C_{oes}$	Output capacitance	$V_{CE} = 25 \text{ V}, f = 1 \text{ MHz}, V_{GE} = 0$	-	196	-	pF
$C_{res}$	Reverse transfer capacitance			39.5		pF
$Q_g$	Total gate charge			126		nC
$Q_{ge}$	Gate-emitter charge	$V_{CE} = 960 \text{ V}, I_C = 30 \text{ A}, V_{GE} = 15 \text{ V}$	-	22.2	-	nC
$Q_{gc}$	Gate-collector charge			67		nC

**Table 6. Switching on/off (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CC} = 960 \text{ V}, I_C = 30 \text{ A}$		48		ns
$t_r$	Current rise time	$R_G = 10 \Omega, V_{GE} = 15 \text{ V},$ (see <a href="#">Figure 16</a> )	-	40	-	ns
$(di/dt)_{on}$	Turn-on current slope			540		A/ $\mu\text{s}$
$t_{d(on)}$	Turn-on delay time	$V_{CC} = 960 \text{ V}, I_C = 30 \text{ A}$		45		ns
$t_r$	Current rise time	$R_G = 10 \Omega, V_{GE} = 15 \text{ V},$	-	38	-	ns
$(di/dt)_{on}$	Turn-on current slope	$T_J = 125^\circ\text{C}$ (see <a href="#">Figure 16</a> )		665		A/ $\mu\text{s}$
$t_r(V_{off})$	Off voltage rise time	$V_{CC} = 960 \text{ V}, I_C = 30 \text{ A}$		84		ns
$t_d(off)$	Turn-off delay time	$R_G = 10 \Omega, V_{GE} = 15 \text{ V},$	-	338	-	ns
$t_f$	Current fall time	(see <a href="#">Figure 16</a> )		210		ns
$t_r(V_{off})$	Off voltage rise time	$V_{CC} = 960 \text{ V}, I_C = 30 \text{ A}$		144		ns
$t_d(off)$	Turn-off delay time	$R_G = 10 \Omega, V_{GE} = 15 \text{ V},$	-	420	-	ns
$t_f$	Current fall time	$T_J = 125^\circ\text{C}$ (see <a href="#">Figure 16</a> )		360		ns

**Table 7. Switching energy (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$E_{on}^{(1)}$ $E_{off}^{(2)}$ $E_{ts}$	Turn-on switching losses	$V_{CC} = 960 \text{ V}$ , $I_C = 30 \text{ A}$ $R_G = 10 \Omega$ , $V_{GE} = 15 \text{ V}$ , (see <a href="#">Figure 16</a> )	-	3.7	-	mJ
	Turn-off switching losses			5.7	-	mJ
	Total switching losses			9.4	-	mJ
$E_{on}^{(1)}$ $E_{off}^{(2)}$ $E_{ts}$	Turn-on switching losses	$V_{CC} = 960 \text{ V}$ , $I_C = 30 \text{ A}$ $R_G = 10 \Omega$ , $V_{GE} = 15 \text{ V}$ , $T_J = 125^\circ\text{C}$ (see <a href="#">Figure 16</a> )	-	4.7	-	mJ
	Turn-off switching losses			9.3	-	mJ
	Total switching losses			14	-	mJ

1.  $E_{on}$  is the turn-on losses when a typical diode is used in the test circuit in [Figure 16](#). If the IGBT is offered in a package with a co-pack diode, the co-pack diode is used as external diode. IGBTs and diode are at the same temperature ( $25^\circ\text{C}$  and  $125^\circ\text{C}$ )
2. Turn-off losses include also the tail of the collector current

**Table 8. Collector-emitter diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_F$	Forward on-voltage	$I_F = 20 \text{ A}$ $I_F = 20 \text{ A}$ , $T_J = 125^\circ\text{C}$	-	1.9 1.7	-	V V
$t_{rr}$ $Q_{rr}$ $I_{rrm}$	Reverse recovery time	$I_F = 20 \text{ A}$ , $V_R = 45 \text{ V}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ (see <a href="#">Figure 19</a> )	-	84	-	ns
	Reverse recovery charge			235	-	nC
	Reverse recovery current			5.6	-	A
$t_{rr}$ $Q_{rr}$ $I_{rrm}$	Reverse recovery time	$I_F = 20 \text{ A}$ , $V_R = 45 \text{ V}$ , $T_J = 125^\circ\text{C}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ (see <a href="#">Figure 19</a> )	-	152	-	ns
	Reverse recovery charge			722	-	nC
	Reverse recovery current			9	-	A

## 2.1 Electrical characteristics (curves)

Figure 2. Output characteristics

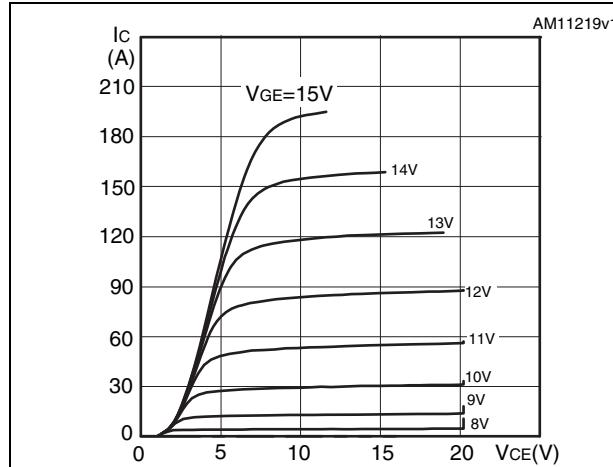


Figure 3. Transfer characteristics

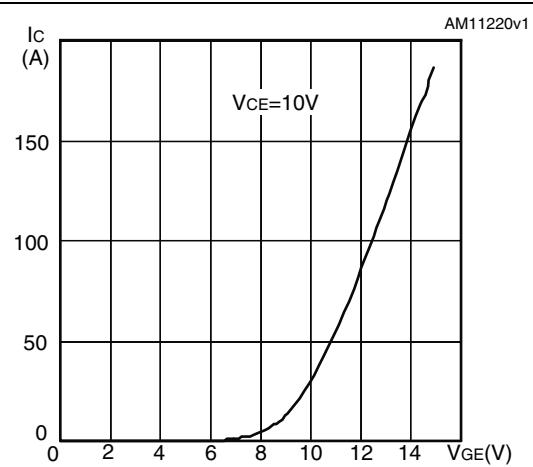


Figure 4. Collector-emitter on voltage vs. collector current

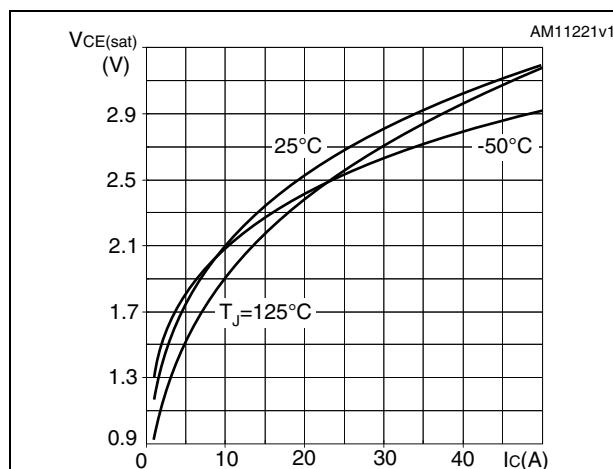


Figure 5. Collector-emitter on voltage vs. temperature

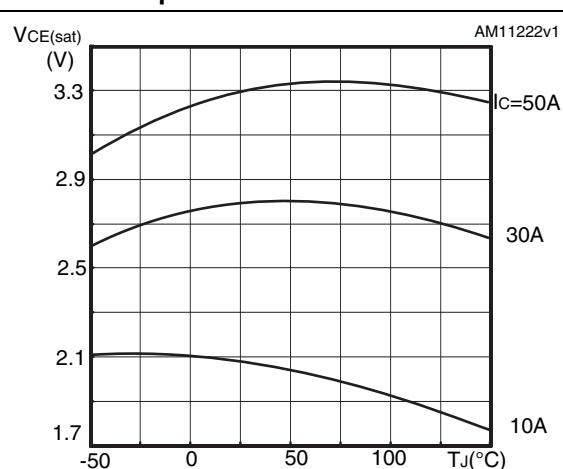


Figure 6. Gate charge vs. gate-source voltage

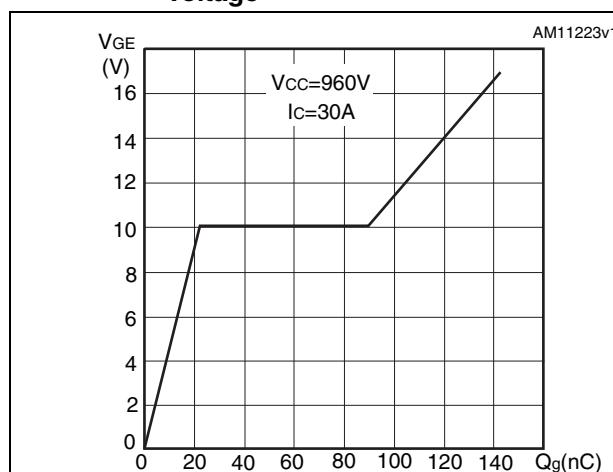
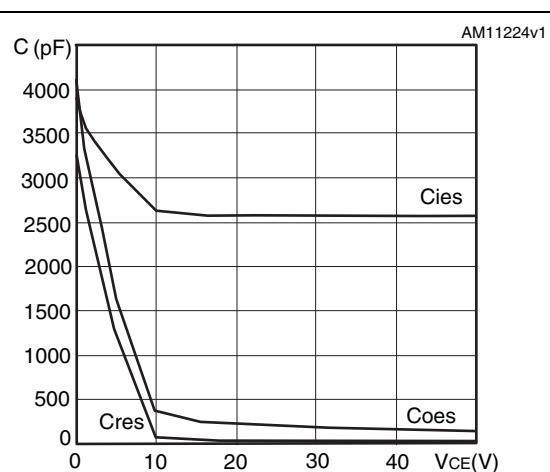
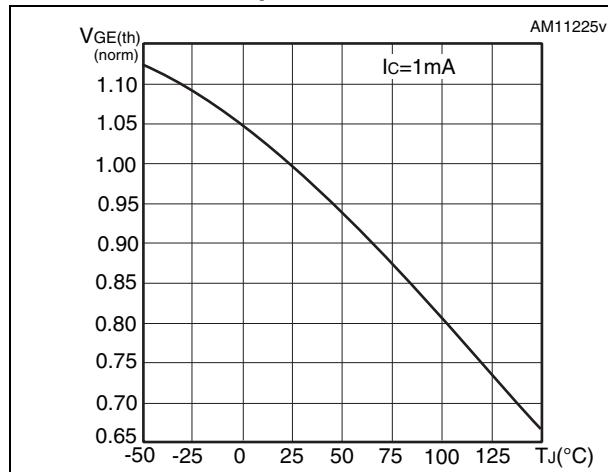
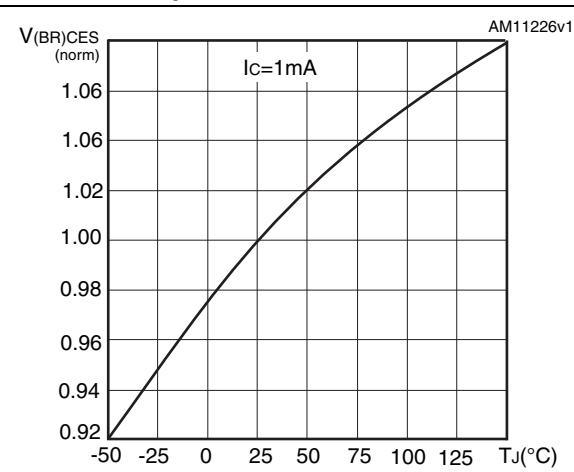
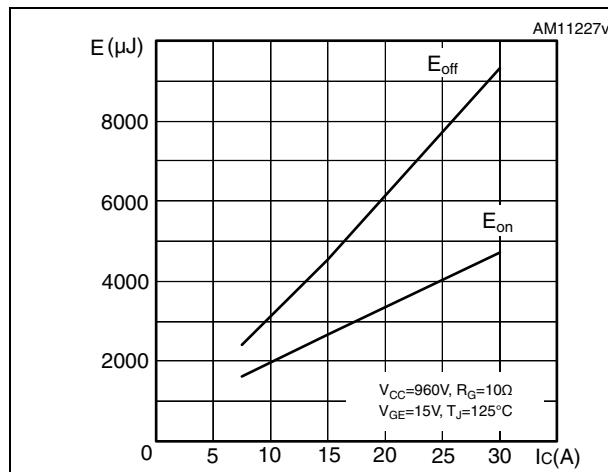
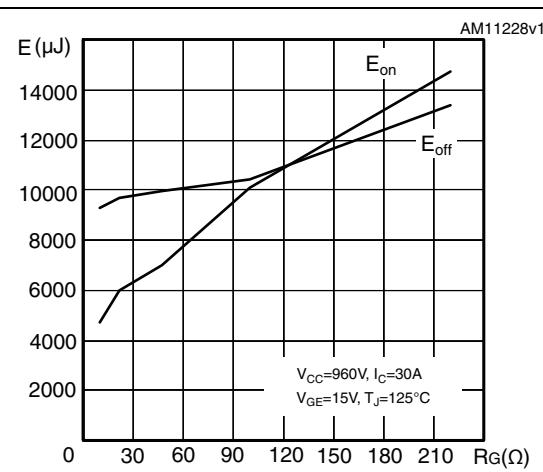
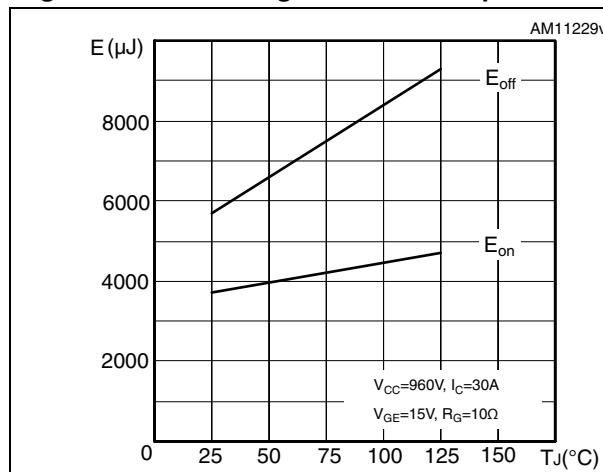
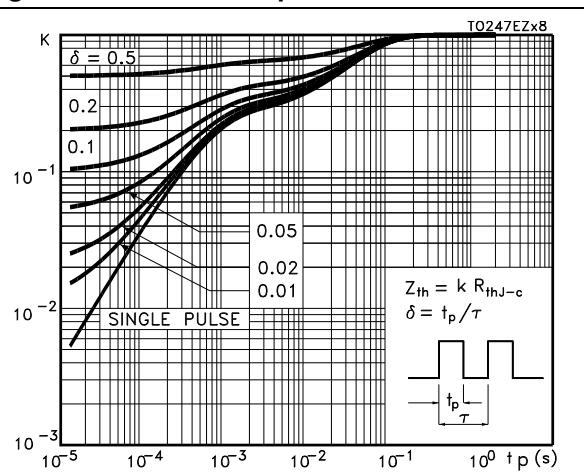
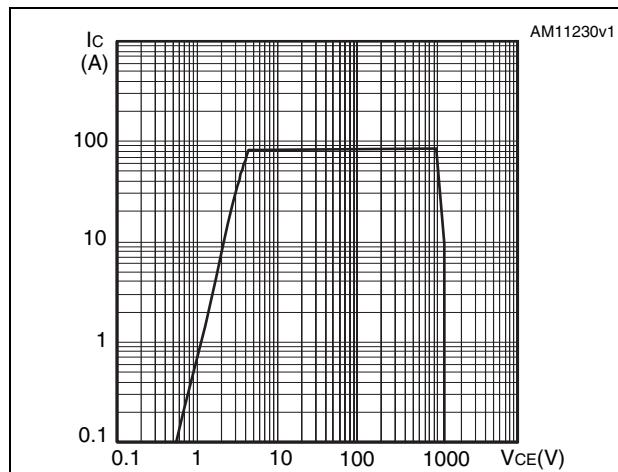
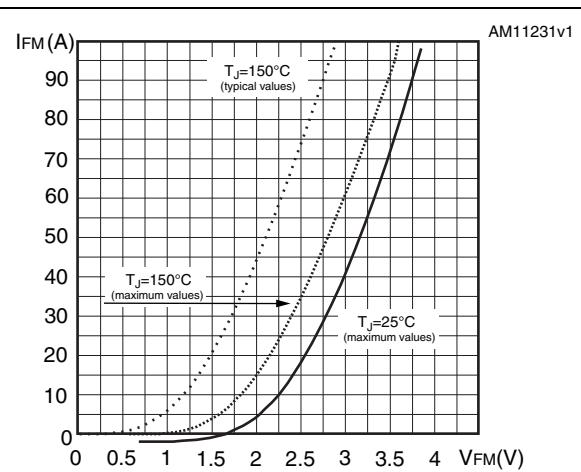


Figure 7. Capacitance variations

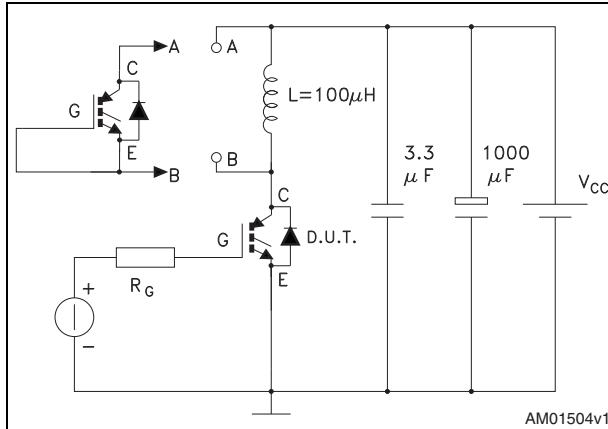


**Figure 8. Normalized gate threshold voltage vs. temperature****Figure 9. Normalized breakdown voltage vs. temperature****Figure 10. Switching losses vs. collector current****Figure 11. Switching losses vs. gate resistance****Figure 12. Switching losses vs. temperature****Figure 13. Thermal impedance**

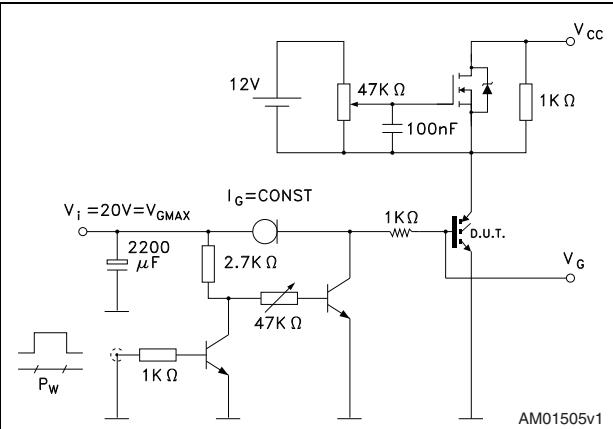
**Figure 14. Turn-off SOA****Figure 15. Forward voltage drop vs. forward current**

### 3 Test circuits

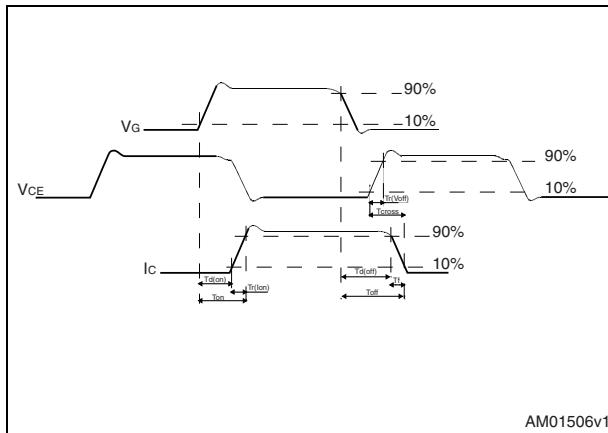
**Figure 16. Test circuit for inductive load switching**



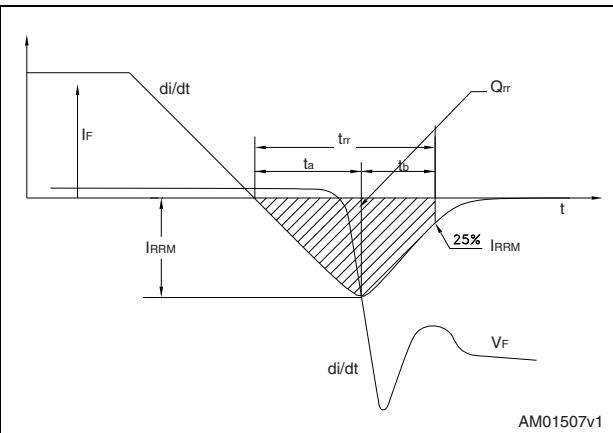
**Figure 17. Gate charge test circuit**



**Figure 18. Switching waveform**



**Figure 19. Diode recovery time waveform**



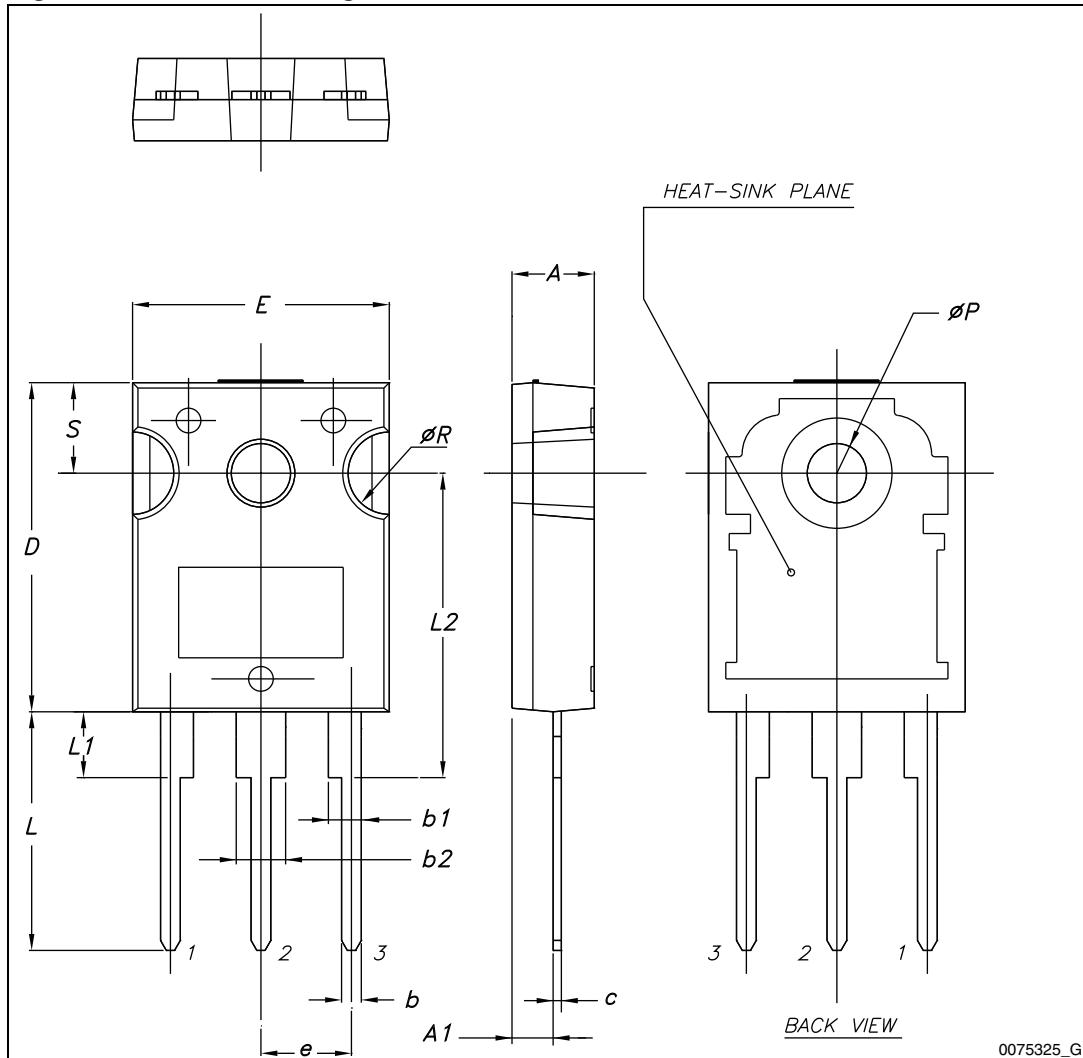
## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

**Table 9. TO-247 mechanical data**

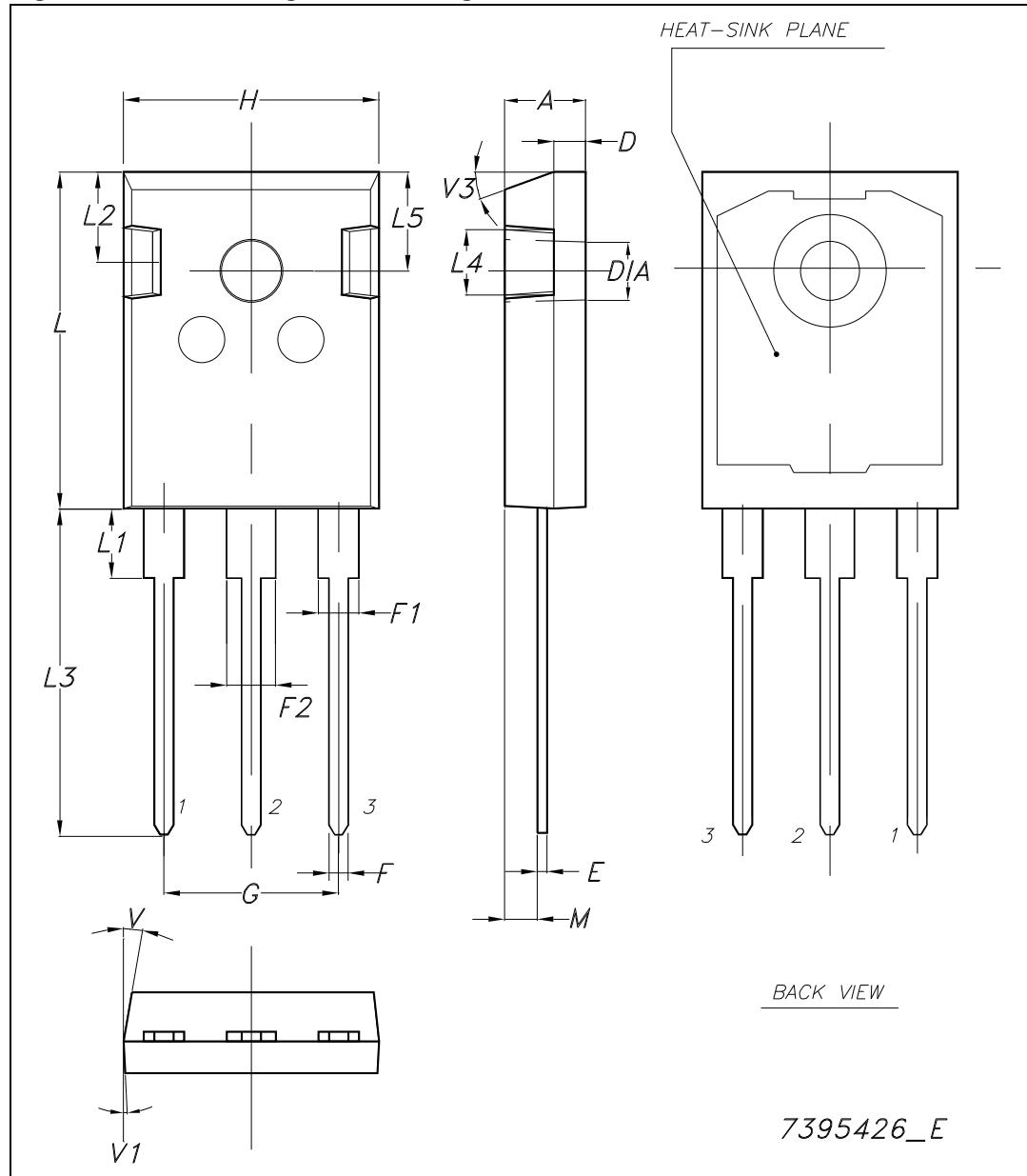
Dim.	mm.		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

Figure 20. TO-247 drawing dimensions



**Table 10.** TO-247 long leads mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.90		5.15
D	1.85		2.10
E	0.55		0.67
F	1.07		1.32
F1	1.90		2.38
F2	2.87		3.38
G	10.90 BSC		
H	15.77		16.02
L	20.82		21.07
L1	4.16		4.47
L2	5.49		5.74
L3	20.05		20.30
L4	3.68		3.93
L5	6.04		6.29
M	2.27		2.52
V		10°	
V1		3°	
V3		20°	
Dia.	3.55		3.66

**Figure 21.** TO-247 long leads drawing

## 5 Revision history

**Table 11. Document revision history**

Date	Revision	Changes
22-Jan-2009	1	Initial release
29-Jun-2009	2	Document status promoted from preliminary data to datasheet.
09-Jul-2009	3	Inserted dynamic values <a href="#">Table 5 on page 4</a> , <a href="#">Table 6 on page 4</a> and <a href="#">Table 7 on page 5</a> .
11-Jan-2012	4	Added order code STGWA40N120KD <a href="#">Table 1 on page 1</a> , <a href="#">Section 2.1 on page 6</a> , mechanical data TO-247 long leads <a href="#">Table 10 on page 12</a> and <a href="#">Figure 21 on page 13</a> .

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